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## **IC Knowledge – IC Cost and Price Model Supported Packages List**

As of the 2018 IC Cost and Price Model revision 01 the following packages are included in the model.

1. Backgrind only
2. Bumped die
3. Bumped die with coating
4. Bumped die with RDL
5. Bumped die with RDL and coating
6. cBGA
7. cLGA
8. cPGA
9. DIP
10. fcBGA
11. fcLGA
12. fcMLF/MLP/QFN
13. fcPGA
14. LQFP
15. MLF/MLP/QFN
16. MQFP
17. No packaging
18. pBGA
19. pLGA
20. pPGA
21. PLCC
22. Reconstructed wafer
23. Saw only
24. SOIC
25. SOJ
26. TQFP
27. TSOP